APPLICABLE S	TAND	ARD								
RATING OPERATING		RANGE	-30°C TO + 85°C(I	NOTE 1)	STORAG	GE RATURE RANGE	-10°C T0 + 60°	C (NOTF	2)	
	TEMPERATURE RANGE OPERATING		ls:		STORAG					
	ITY RANG	E	40% T0 + 80	%		Y RANGE	40% T0 + 70%	•	ΓΕ 2)	
VOLTA	TAGE		AC 250V AWG 22 TO 26 :	2A	VOLTA	GE	AC 30\ AWG 22 :	AC 30V		
CURRENT				∠A 1A	CURRE	ENT	AWG 24 TO 28 :	2A 1A	2A 1A	
		AWG 30 : 0.5A				AWG 30 : 0.5				
<u> </u>				IFICA	LIONS	<u> </u>	7.11.0	*****		
				1071	11011		OUIDEMENTS	I OT	LAT	
CONSTRUCTI	ION _		TEST METHOD			KE	QUIREMENTS	QT	AT	
GENERAL EXAMINATI		/ISUALLY	AND BY MEASURING INSTRU	JMENT.	AC	CORDING TO	DRAWING.	X	X	
MARKING		CONFIRMED VISUALLY.						X		
ELECTRIC CH	IARAC	TERIS	STICS		l					
CONTACT RESISTAN	NCE	100 mA (	DC OR 1000 Hz).		30	D mΩ MAX.		Х	T —	
INSULATION RESISTANCE		500 V DC.			10	000 MΩ MIN.		X	1-	
VOLTAGE PROOF		650 V AC FOR 1 min.			NO	NO FLASHOVER OR BREAKDOWN.			+-	
MECHANICAL CHA						1				
MECHANICAL OPER			S INSERTIONS AND EXTRA	CTIONS.	10	CONTACT RES	SISTANCE: 30mΩ MAX.			
						② NO DAMAGE, CRACK OR LOOSENESS OF			_	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE				PARTS.  ① NO ELECTRICAL DISCONTINUITY OF 1μs.				
		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.				© NO DAMAGE, CRACK OR LOOSENESS OF				
SHOCK		490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				PARTS.		X		
ENVIRONMEN					l					
RAPID CHANGE OF			TURE -55→ 5 TO 35→+85	→ 5 TO 35	°C ①	CONTACT RESI	STANCE: 30mΩ MAX.			
TEMPERATURE		TIME $30 \rightarrow 5$ TO $15 \rightarrow 30 \rightarrow 5$ TO15 min UNDER 5 CYCLES.			3		SISTANCE: 1000MΩ MIN. RACK OR LOOSENESS OF	X	_	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2	<ul> <li>⊕ CONTACT RESISTANCE: 30mΩ MAX.</li> <li>② INSULATION RESISTANCE: 500MΩ MIN.</li> <li>③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.</li> </ul>			-	
RESISTANCE TO SOLDERING HEAT		1) AUTOMATIC SOLDERING (REFLOW)  《REFLOW AREA》			l	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			_	
		MAX 240°C WITHIN 10 sec. MIN 220°C WITHIN 60sec.  《PREHEATING AREA》  150 TO 180°C 90 TO 120 sec. PUT THROUGH IN REFROW FURNACE TWICE. FEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNEVCTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW.  2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290 ± 10°C, SOLDERING TIME :3s.								
		NO STRENGTH ON CONTACT. SOLDERED AT SOLDER TEMPERATURE.			ΔN	A NEW UNIFORM COATING OF SOLDER SHALL				
SOLDERABILITY	9	KULUERE	DIN OCEDEN IEM ENVI	OIL,			OF 95 % OF THE SURFACE			
SOLDERABILITY			FOR IN IMMERSION , DURA	ATION, 3 s.		ING IMMERSED		X		
COUNT	2	230±5°C	FOR IN IMMERSION , DURA ON OF REVISIONS	· · · · · · · · · · · · · · · · · · ·		ING IMMERSED			ATE	
COUNT	2	230±5°C	·	· · · · · · · · · · · · · · · · · · ·	ВЕ	ING IMMERSED	. CHECKED TS.SAKATA	D/ 06.	09.08	
COUNT 1 REMARKS	DES	230±5°C SCRIPTIO	N OF REVISIONS H-001311	· · · · · · · · · · · · · · · · · · ·	BE DESIGNE	ED APPROVI	. CHECKED TS.SAKATA ED TS.MIYAZAKI	06. 05.	09.08 02.14	
COUNT  1 REMARKS NOTE 1:INCLUDING TH	DES  E TEMPER E CONDITION	CRIPTIC DIS- RATURE RI DN OF LON	ON OF REVISIONS H-001311 SE BY CURRENT. IG TERM STORAGE FOR UNI	JSED PRODL	BE DESIGNE AK.MIURA ICTS	APPROVI	CHECKED TS.SAKATA ED TS.MIYAZAKI CD HK.UMEHARA	06. 05.	09.08 02.14 02.08	
COUNT  1 REMARKS NOTE 1:INCLUDING TH NOTE 2:APPLY TO THE BEFORE PCB (	DES  E TEMPEF E CONDITION ON BOARD	230±5°C  DIS-  RATURE RI DN OF LON  AFTER F	ON OF REVISIONS H-001311 SE BY CURRENT.	JSED PRODU	BE DESIGNE AK.MIURA ICTS IND	APPROVI CHECKE DESIGNE	CHECKED TS.SAKATA ED TS.MIYAZAKI ED HK.UMEHARA ED 10.DENPOUYA	06. 05. 05.	09.08 02.14 02.08 01.28	
COUNT  1 REMARKS NOTE 1:INCLUDING TH NOTE 2:APPLY TO THE BEFORE PCB 0 HUMIDITY RAN Juless otherwise specifications	DES  E TEMPER E CONDITION ON BOARD IGE IS APP fid , refer to	CORIPTICE DIS- RATURE RIDN OF LONDO, AFTER FULIED FOR DISC 54	ON OF REVISIONS  H-001311  SE BY CURRENT.  IG TERM STORAGE FOR UNICED BOARD, OPERATING TEM INTERM STORAGE DURING THE 102.	USED PRODU IPERATURE A RANSPORTAT	BE DESIGNE AK.MIURA ICTS ICTS IND ION.	APPROVI CHECKE DESIGNE	CHECKED TS.SAKATA ED TS.MIYAZAKI ED HK.UMEHARA ED IO.DENPOUYA N FK.MATSUKI	06. 05. 05. 05.	09.08 02.14 02.08	
COUNT  1 REMARKS NOTE 1:INCLUDING TH NOTE 2:APPLY TO THE BEFORE PCB 0 HUMIDITY RAN Unless otherwise specif	DES DES DE TEMPER CONDITION DON BOARD IGE IS APP fid , refer to	CRIPTIC DIS- RATURE RI DN OF LON D, AFTER F PLIED FOR D JIS C 54 AT:ASSU	ON OF REVISIONS  H-001311  SE BY CURRENT.  IG TERM STORAGE FOR UNL  PCB BOARD, OPERATING TEM  INTERM STORAGE DURING TF  02.  Irance Test X:Applicable Te	JSED PRODL IPERATURE A RANSPORTAT	DESIGNE  AK.MIURA  ICTS IND TION.  DRAV	APPROVI CHECKE DESIGNE DRAWN	CHECKED TS.SAKATA ED TS.MIYAZAKI ED HK.UMEHARA ED 10.DENPOUYA FK.MATSUKI ELC4-3060	06. 05. 05. 05.	09.08 02.14 02.08 01.28	
COUNT  1 REMARKS NOTE 1:INCLUDING TH NOTE 2:APPLY TO THE BEFORE PCB 0 HUMIDITY RAN Unless otherwise specif	DES  E TEMPER E CONDITION BOARD IGE IS APP fid , refer to ion Test	CRIPTIC DIS- RATURE RI DN OF LON D. AFTER F PLIED FOR D JIS C 54 AT:Assu	ON OF REVISIONS  H-001311  SE BY CURRENT.  IG TERM STORAGE FOR UNICED BOARD, OPERATING TEM INTERM STORAGE DURING THE 102.	JSED PRODU IPERATURE A RANSPORTAT	BE DESIGNE AK.MIURA ICTS ICTS IND ION.	APPROVI CHECKE DESIGNE DRAWN	CHECKED TS.SAKATA ED TS.MIYAZAKI ED HK.UMEHARA ED IO.DENPOUYA N FK.MATSUKI	06. 05. 05. 05.	09.08 02.14 02.08 01.28	